FleXus Film Stress Measurement

Manager: Jerry Drumheller
Backup: Phil Infante

Work Phone
Manager: 254-4859
Backup: 254-4926

Safety
- No unusual hazards during normal operation
- No buddy system restrictions imposed on normal operation

Process Restrictions
Material Restrictions
- Whole wafers only
- Wafer top surface must reflect a laser beam, without too much scatter.
- Wafer/substrate material must be included in the Flexus software list of material data.

Parameter Restrictions
- 4", 6", 8" whole wafers only.

Scheduling / Sign-up Restrictions -- Minimum Tool Time: 15 minutes
- Maximum 6 hour block reservations anytime - Maximum 12 hours reserved in advance at any time per person - No consecutive research group reservations - Users/Groups may use any amount of unreserved time - Additional individual restrictions may be imposed to maximize effective use

Requirements (Do Every Time)
- Turn off laser and front power switch when finished.
- Save your data to a USB memory device when finished.

Prohibitions (Never Do)
- NEVER Delete files from computer without permission from machine manager.
- NEVER Leave the N2 flow on when you are finished.

Common Problems

<table>
<thead>
<tr>
<th>Problem:</th>
<th>Root Cause:</th>
<th>Solution:</th>
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<tbody>
<tr>
<td>- Won't scan - intensity too low error</td>
<td>1. Laser off&lt;br&gt;2. Wafer has a dielectric which is not reflective to 670nm or 780nm light&lt;br&gt;3. Wafer has highly reflective coating and both lasers are selected</td>
<td>1. Turn on laser&lt;br&gt;2. See tool manager&lt;br&gt;3. Signal is too great. Chose one laser or automatic laser</td>
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</table>

Other Comments or Cautions
- OK to call machine manager about malfunctions Before 10:00 p.m. and after 9:00 am(Weekends).

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.